

## Preface

The 20<sup>th</sup> International Symposium on Processing and Fabrication of Advanced Materials (PFAMXX) was organized by The Hong Kong Polytechnic University 15-17 December 2011, Hong Kong. The primary purpose of this inter-disciplinary symposium is to bring together state-of-the-art developments on all aspects related to the processing and fabrication of advanced materials spanning the entire spectrum of metallic, intermetallics, ceramics, ceramic-matrix composites, metal-matrix composites, intermetallic-matrix composites, advanced polymers and polymer-matrix composites, and including surface and high-temperature coatings. The symposium will certainly provide an attractive forum for presenting the latest advances in materials processing and fabrication by researchers and engineers from industry, research laboratories and academia. This proceedings is to bring all peer-reviewed articles from different disciplines to be bound as a valuable reading material for researchers and scientists as a reference to learn frontier works in relation to processing and fabrication of new materials. The topics covered in this proceedings are in the following areas:

- Advanced Composite Materials (Polymer, Metal and Ceramics)
- Natural Fibre (Plant or Animal based) Composites
- Nano-structural Materials
- Properties of Materials
- Failure Analysis
- Computational Analysis and Simulations
- Advanced Manufacturing Processes
- Bio-materials and Bio-composites
- Materials Characterizations

Here the editors would like to express our sincere thank to all the authors and co-authors for their scientific contribution to this proceedings. We convey our gratitude to all the reviewers for their time and dedication. We applaud Trans Tech Publications Inc for their support and encouragement of this proceedings and their staff for their special attention and timely response.

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